



Material Content Data Sheet



Halogen-Free

Sales Product Name	BCX 55 H6327	Issued	04. May 2021
MA#	MA001201656		
Package	PG-SOT89-4-3	Weight*	53.15 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.003	0.01		51	
	noble metal	gold	7440-57-5	0.011	0.02		200	
	inorganic material	silicon	7440-21-3	0.129	0.24	0.27	2436	2687
leadframe	inorganic material	silicon	7440-21-3	0.005	0.01		95	
	non noble metal	titanium	7440-32-6	0.025	0.05		474	
	non noble metal	chromium	7440-47-3	0.076	0.14		1423	
	non noble metal	copper	7440-50-8	25.112	47.23	47.43	472478	474470
wire	non noble metal	copper	7440-50-8	0.051	0.10	0.10	953	953
encapsulation	organic material	carbon black	1333-86-4	0.269	0.51		5054	
	plastics	epoxy resin	-	4.029	7.58		75815	
	inorganic material	silicondioxide	60676-86-0	22.565	42.46	50.55	424562	505431
leadfinish	non noble metal	tin	7440-31-5	0.801	1.51	1.51	15076	15076
plating	noble metal	silver	7440-22-4	0.073	0.14	0.14	1383	1383
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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